

## Features

- Split Gate Trench MOSFET Technology
- High Density Cell Design For Low  $R_{DS(ON)}$
- Moisture Sensitivity Level 1
- Halogen Free. "Green" Device <sup>(Note1)</sup>
- Epoxy Meets UL 94 V-0 Flammability Rating
- Lead Free Finish/RoHS Compliant ("P" Suffix Designates RoHS Compliant. See Ordering Information)

## Maximum Ratings

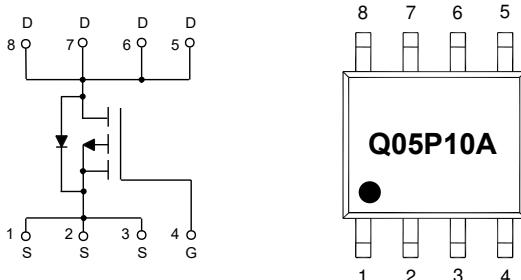
- Operating Junction Temperature Range : -55°C to +150°C
- Storage Temperature Range: -55°C to +150°C
- Thermal Resistance: 75°C/W Junction to Ambient(Steady-State) <sup>(Note2)</sup>
- Thermal Resistance: 24°C/W Junction to Lead(Steady-State)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	$V_{DS}$	-100	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current <small><math>T_A=25^\circ C</math></small>	$I_D$	-4.5	A
		-2.8	
Pulsed Drain Current <sup>(Note3)</sup>	$I_{DM}$	-18	A
Total Power Dissipation <sup>(Note4)</sup>	$P_D$	1.6	W
Single Pulsed Avalanche Energy <sup>(Note5)</sup>	$E_{AS}$	56	mJ

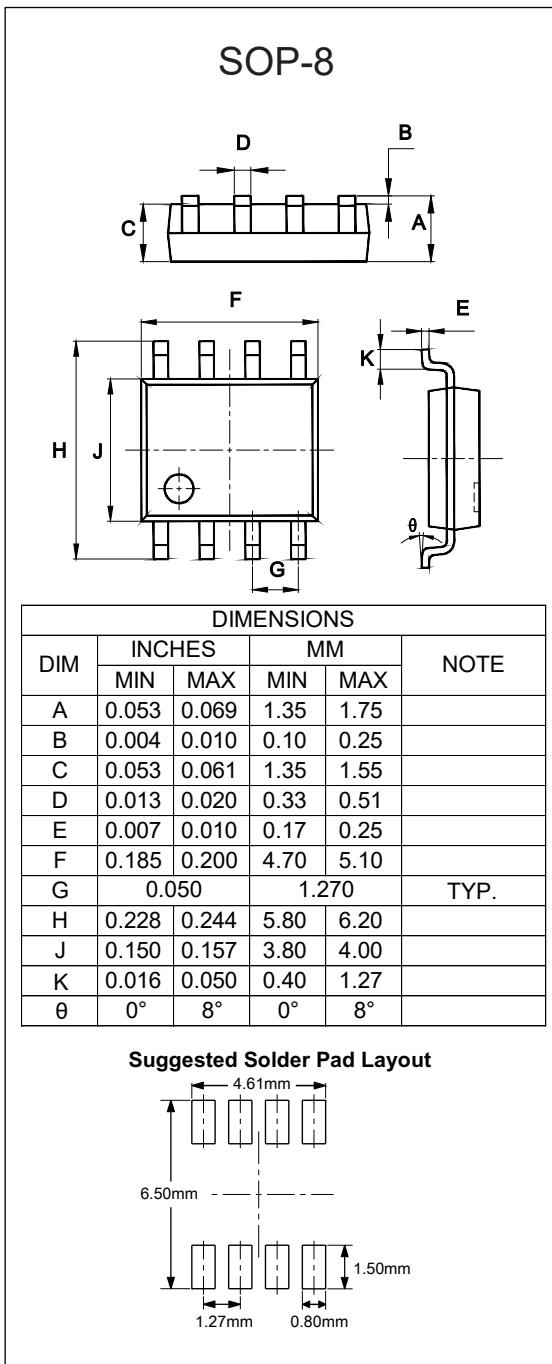
Note:

1. Halogen free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
2. The value of  $R_{\theta JA}$  is measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_A = 25^\circ C$ . The Power dissipation  $P_{DSM}$  is based on  $R_{\theta JA} \leq 10$ s and the maximum allowed junction temperature of 150°C. The value in any given application depends on the user's specific board design.
3. Repetitive rating; pulse width limited by max. junction temperature.
4.  $P_D$  is based on max. junction temperature, using junction-ambient thermal resistance.
5.  $T_J=25^\circ C$ ,  $V_{DD}=-30V$ ,  $V_{GS}=-10V$ ,  $L=0.5mH$

## Internal Structure and Marking Code



## P-CHANNEL MOSFET



**Electrical Characteristics @ 25°C (Unless Otherwise Specified)**

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>Static Characteristics</b>						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=-250\mu A$	-100			V
Gate-Source Leakage Current	$I_{GSS}$	$V_{DS}=0V, V_{GS}=\pm 20V$			$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=-100V, V_{GS}=0V$			-1	$\mu A$
Gate-Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=-250\mu A$	-1.0	-1.8	-2.5	V
Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=-10V, I_D=-3A$		83	110	$m\Omega$
		$V_{GS}=-4.5V, I_D=-2A$		95	120	
Gate Resistance	$R_g$	F=1 MHz, Open drain		9.8		$\Omega$
<b>Diode Characteristics</b>						
Continuous Body Diode Current	$I_S$				-4.5	A
Diode Forward Voltage	$V_{SD}$	$V_{GS}=0V, I_S=-3A$			-1.3	V
Reverse Recovery Time	$t_{rr}$	$I_S=-5A, dI_F/dt=100A/\mu s$		40		ns
Reverse Recovery Charge	$Q_{rr}$			80		nC
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{iss}$	$V_{DS}=-50V, V_{GS}=0V, f=1MHz$		1062		$pF$
Output Capacitance	$C_{oss}$			112		
Reverse Transfer Capacitance	$C_{rss}$			8.7		
Total Gate Charge	$Q_g$	$V_{DS}=-50V, V_{GS}=-10V, I_D=-5A$		19		$nC$
Gate-Source Charge	$Q_{gs}$			3		
Gate-Drain Charge	$Q_{gd}$			3.5		
Turn-On Delay Time	$t_{d(on)}$	$V_{DD}=-50V, V_{GS}=-10V, R_{GEN}=6\Omega, I_D=-5A$		7.4		$ns$
Turn-On Rise Time	$t_r$			9.3		
Turn-Off Delay Time	$t_{d(off)}$			58		
Turn-Off Fall Time	$t_f$			19		

## Curve Characteristics

Fig. 1 - Typical Output Characteristics

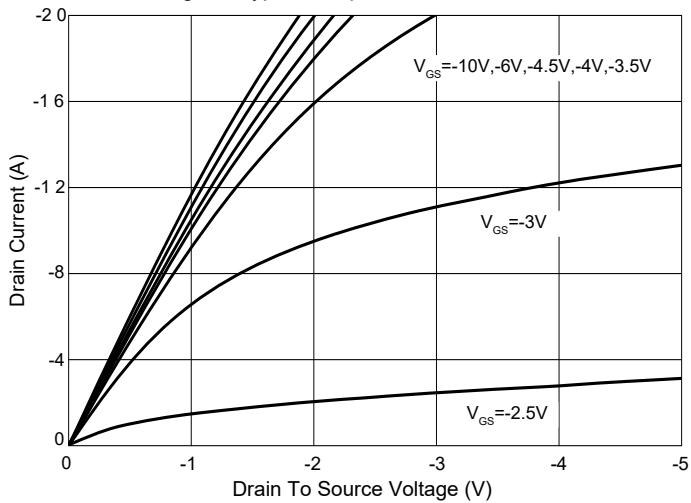


Fig. 2 - Transfer Characteristics

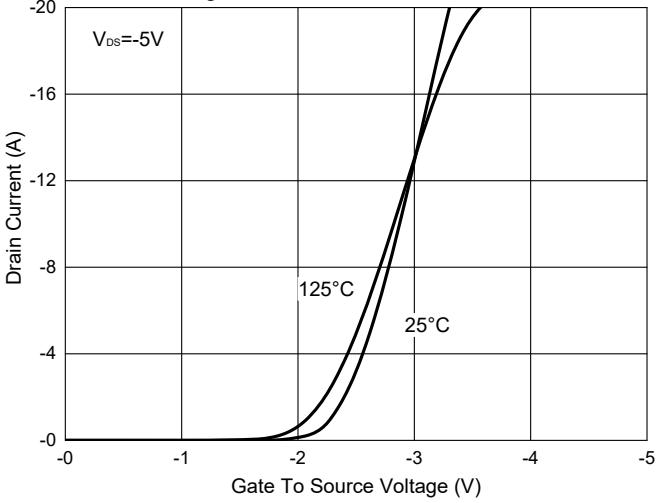


Fig. 3 -  $R_{DS(ON)}$  —  $V_{GS}$

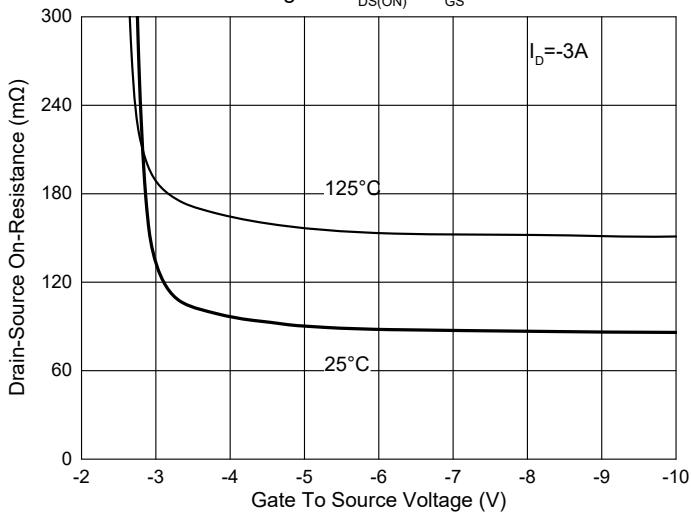


Fig. 4 -  $R_{DS(ON)}$  —  $I_D$

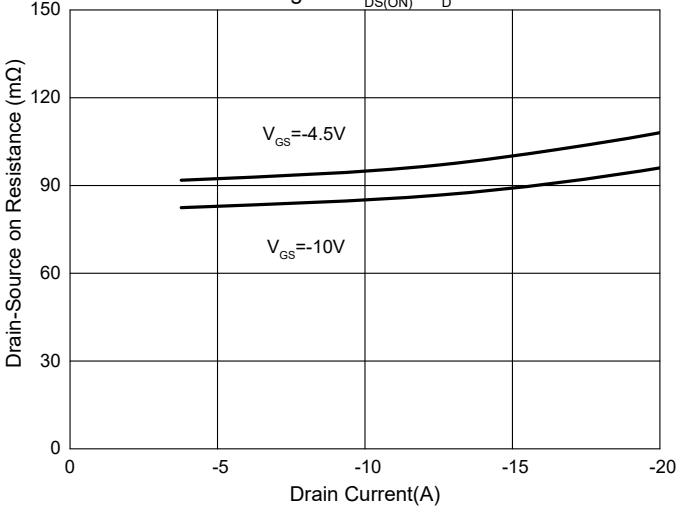


Fig. 5 - Capacitance Characteristics

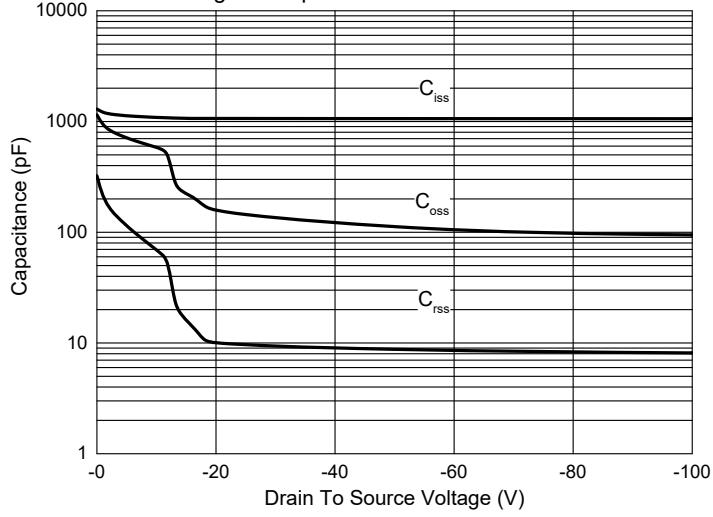
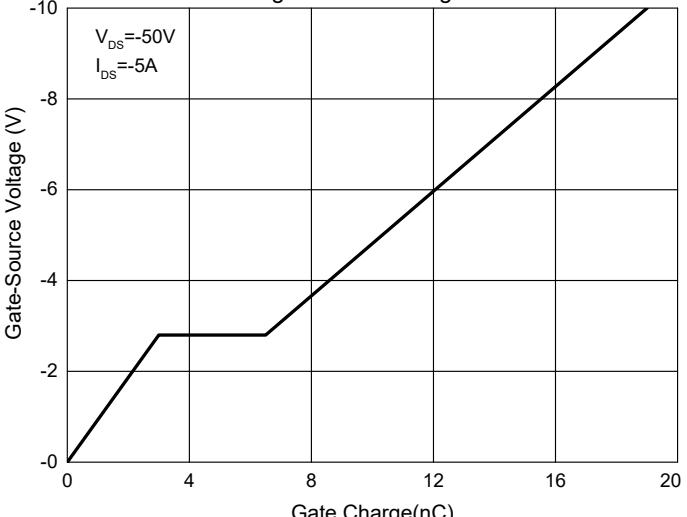
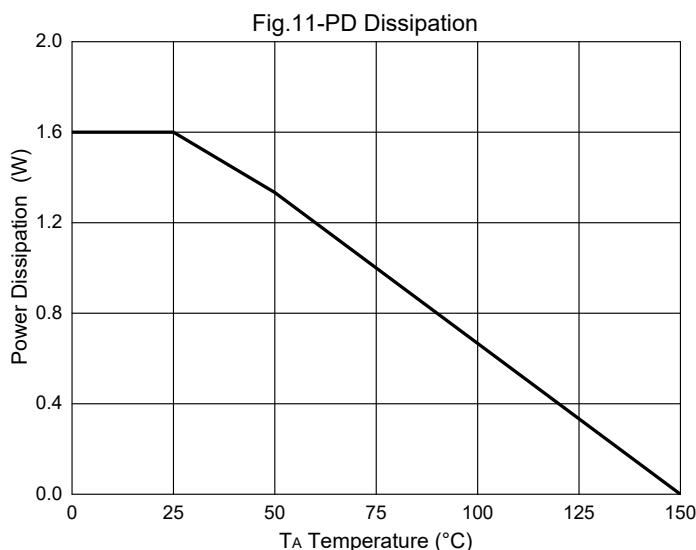
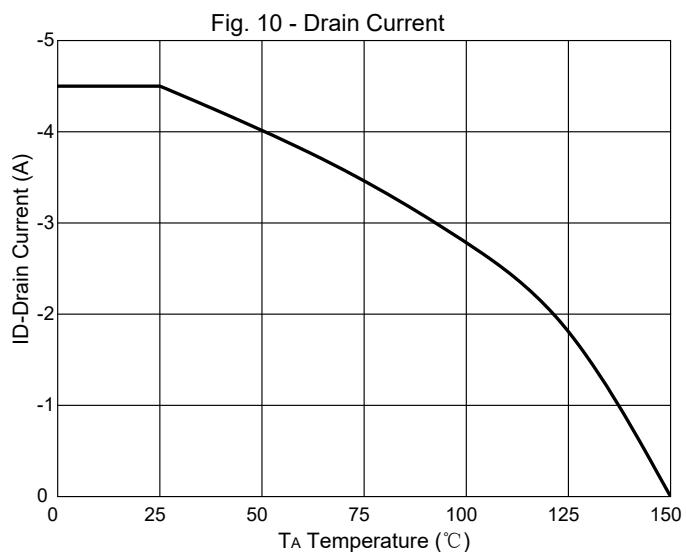
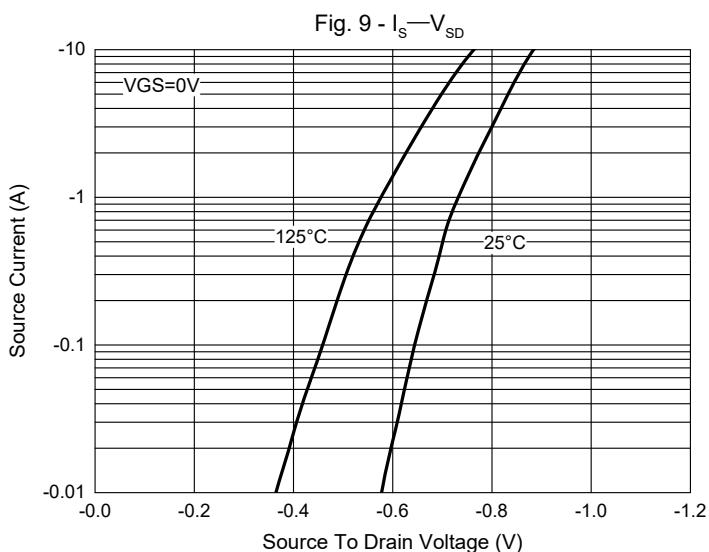
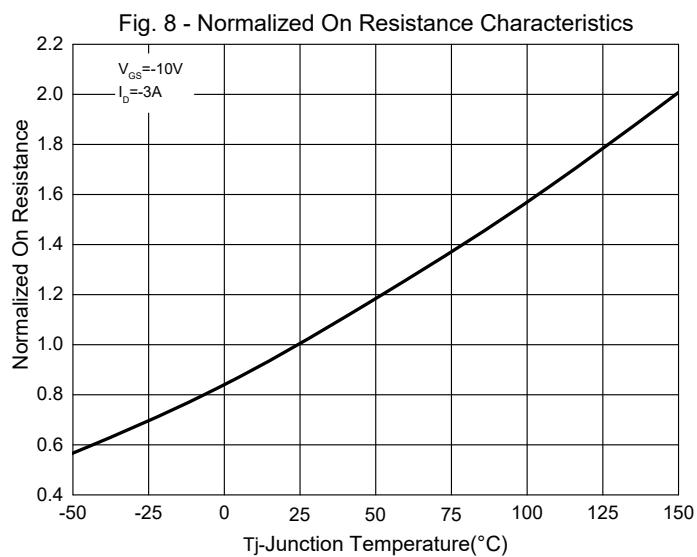
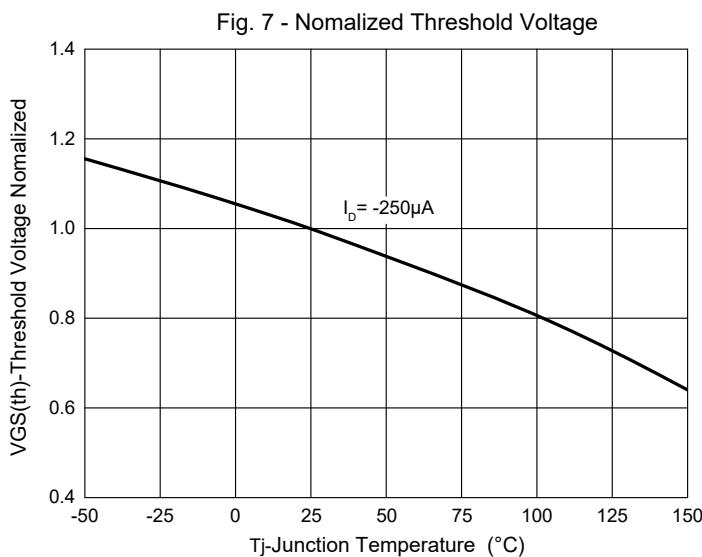


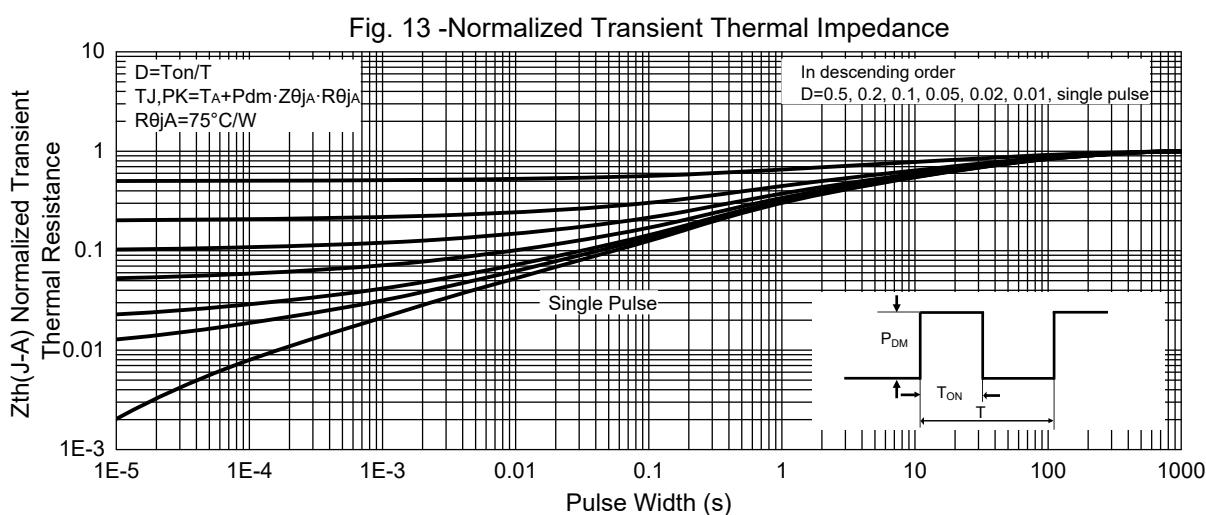
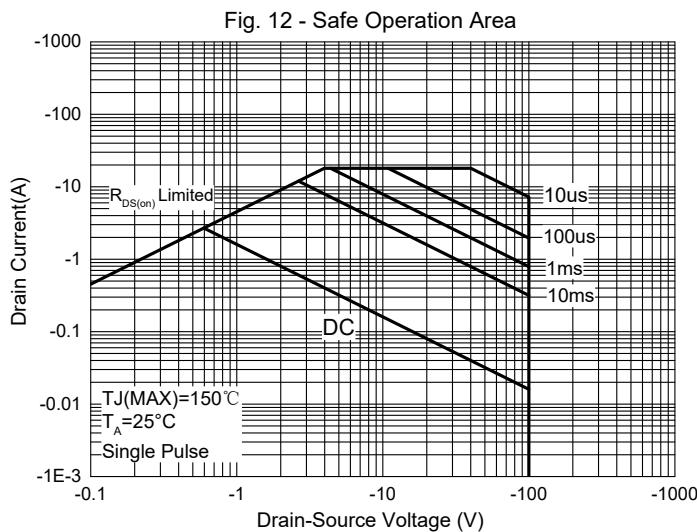
Fig. 6 - Gate Charge



## Curve Characteristics



## Curve Characteristics



## Ordering Information

Device	Packing
Part Number-TP	Tape&Reel: 4Kpcs/Reel

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